



AOS Thermal Compounds, LLC

AOS NON-SILICONE HTC-60

Product Code: 52031

TECHNICAL DATA SHEET

Product Description

AOS Non-Silicone HTC-60 (Higher Thermal Conductivity) Heat Sink Compound was developed by AOS in response to the growing demand in microelectronics for increased thermal transfer efficiency.

- The product retains all the unique advantages of AOS Heat Sink Compound (product code 52022) but has **over four times** the *thermal conductivity* of our standard non-silicone heat sink compound.
- As with our entire line of Heat Sink Compounds, the AOS technical staff can modify **AOS Non-Silicone HTC-60** to meet your exacting specifications.

Typical Properties

<u>Property</u>	<u>Value</u>	<u>Test Method</u>
Consistency (Penetration, worked, 60x)	250-350	ASTM D-217
Specific Gravity , @ 25°C	2.6	ASTM D-70
Bleed , @ 200°C, 24 Hrs., %/Wt	0.3	FTM-321 MODIFIED
Evaporation , @ 200°C, 24 Hrs., %/Wt.	0.50	FTM-321 MODIFIED
Thermal Conductivity , @ 36°C		
Cal/Sec. Cm.°C	59.9 x 10 ⁻⁴	HOT WIRE METHOD
BTU.In/(Hr.Ft ² .°F)	17.4	PER MIL-C-47113B
W/m.°K	2.51	
Electrical Properties		
Dielectric Strength, 0.05" gap, V/mil	351	ASTM D-149
Dielectric Constant, 25°C @ 1,000 Hz	4.92	ASTM D-150
Dissipation Factor, 25°C @ 1,000 Hz	0.0032	ASTM D-150
Volume Resistivity, ohm-cm	1.16 x 10 ¹⁴	ASTM D-257
Operating Temperature Range	-40°C to 200°C	
Flow Rate grams/min.	2 to 15	AOS Method
Appearance	Smooth, Gray Paste	

Please know that customers are responsible for testing AOS Thermal Compounds materials for their proposed use. Any information furnished by AOS Thermal Compounds and its agents is believed to be reliable, but AOS Thermal Compounds does not guarantee the results to be accurate and makes no warranties as to the fitness, merchantability, or suitability of any AOS material or product for any specific or general use and shall not be held liable for incidental or consequential damages of any kind. (040201)